

FEATURES

- Low Reverse Recovery Charge
- High Switching Speed
- Low Forward Volt Drop
- Isolated AISiC Base with AlN Substrates
- Dual Diodes can be paralleled for 1800A Rating
- Lead Free Construction

APPLICATIONS

- Chopper Diodes
- Boost and Buck Circuits
- Free-wheel Circuits
- Multi-level Switch Inverters

The DFM900FXM18-A000 is a dual 1800V, fast recovery diode (FRD) module. Designed for low power loss, the module is suitable for a variety of high voltage applications in motor drives and power conversion.

Fast switching times and low reverse recovery losses allow high frequency operation, making the device suitable for the latest drive designs employing PWM and high frequency switching.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise grounded heat sinks for safety.

ORDERING INFORMATION

Order As:

DFM900FXM18-A000

Note: When ordering, please use the complete part number

KEY PARAMETERS

V_{RRM}		1800V
V_F	(typ)	2.0V
I_F	(max)	900A
I_{FM}	(max)	1800A

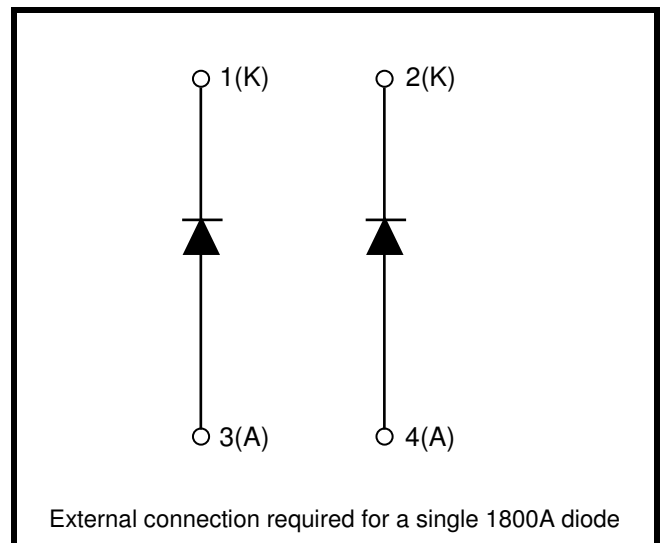


Fig. 1 Circuit configuration

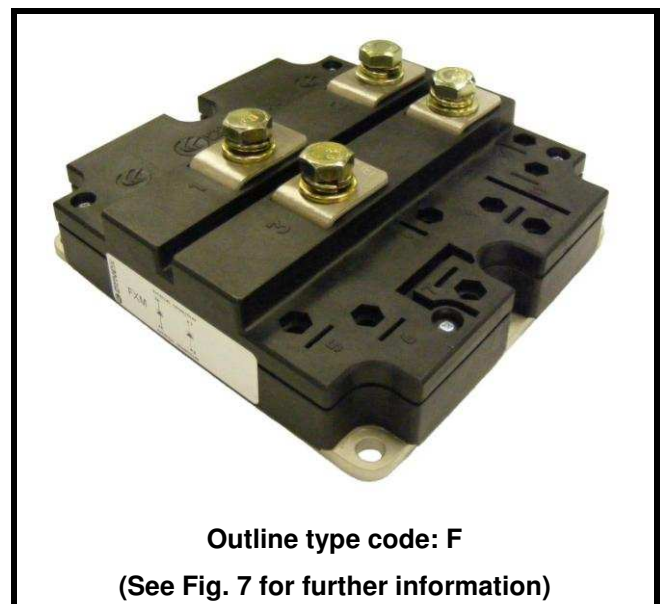


Fig. 2 Package

ABSOLUTE MAXIMUM RATINGS

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

$T_{\text{case}} = 25\text{ °C}$ unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
V_{RRM}	Repetitive peak reverse voltage	$T_j = 125\text{ °C}$	1800	V
I_{F}	Forward current (per arm)	DC, $T_{\text{case}} = 75\text{ °C}$, $T_j = 125\text{ °C}$	900	A
I_{FM}	Max. forward current	$T_{\text{case}} = 110\text{ °C}$, $t_p = 1\text{ ms}$	1800	A
I^2t	I^2t value fuse current rating	$V_R = 0$, $t_p = 10\text{ ms}$, $T_j = 125\text{ °C}$	270	kA^2s
P_{max}	Max. transistor power dissipation	$T_{\text{case}} = 25\text{ °C}$, $T_j = 125\text{ °C}$	3700	W
V_{isol}	Isolation voltage – per module	Commoned terminals to base plate. AC RMS, 1 min, 50Hz	4000	V
Q_{PD}	Partial discharge – per module	IEC1287, $V_1 = 1900\text{ V}$, $V_2 = 1400\text{ V}$, 50Hz RMS	10	pC

THERMAL AND MECHANICAL RATINGS

Internal insulation material:	AlN
Baseplate material:	AlSiC
Creepage distance:	20mm
Clearance:	10mm
CTI (Comparative Tracking Index):	350

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
$R_{\text{th(j-c)}}$	Thermal resistance (per arm)	Continuous dissipation – junction to case	-	-	27	°C/kW
$R_{\text{th(c-h)}}$	Thermal resistance – case to heatsink (per module)	Mounting torque 5Nm (with mounting grease)	-	-	8	°C/kW
T_j	Junction temperature		-	-	125	°C
T_{stg}	Storage temperature range		-40	-	125	°C
	Screw Torque	Mounting – M6	-	-	5	Nm
		Electrical connections – M8	-	-	10	Nm

STATIC ELECTRICAL CHARACTERISTICS – PER ARM
T_{case} = 25 °C unless stated otherwise.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
I _{RM}	Peak reverse current	V _R = 1800V, T _j = 125 °C			15	mA
V _F	Forward voltage	I _F = 900A		2.0	2.3	V
		I _F = 900A, T _j = 125 °C		2.0	2.3	V
L _M	Inductance			20		nH

STATIC ELECTRICAL CHARACTERISTICS
T_{case} = 25 °C unless stated otherwise.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
L _M	Module inductance (externally connected in parallel)			15		nH

DYNAMIC ELECTRICAL CHARACTERISTICS – PER ARM
T_{case} = 25 °C unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
Q _{rr}	Reverse recovery charge	I _F = 900A V _R = 900V di _F /dt = 6000A/μs		240		μC
I _{rr}	Peak reverse recovery current			660		A
E _{rec}	Reverse recovery energy			180		mJ

T_{case} = 125 °C unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
Q _{rr}	Reverse recovery charge	I _F = 900A V _R = 900V di _F /dt = 6000A/μs		410		μC
I _{rr}	Peak reverse recovery current			765		A
E _{rec}	Reverse recovery energy			270		mJ

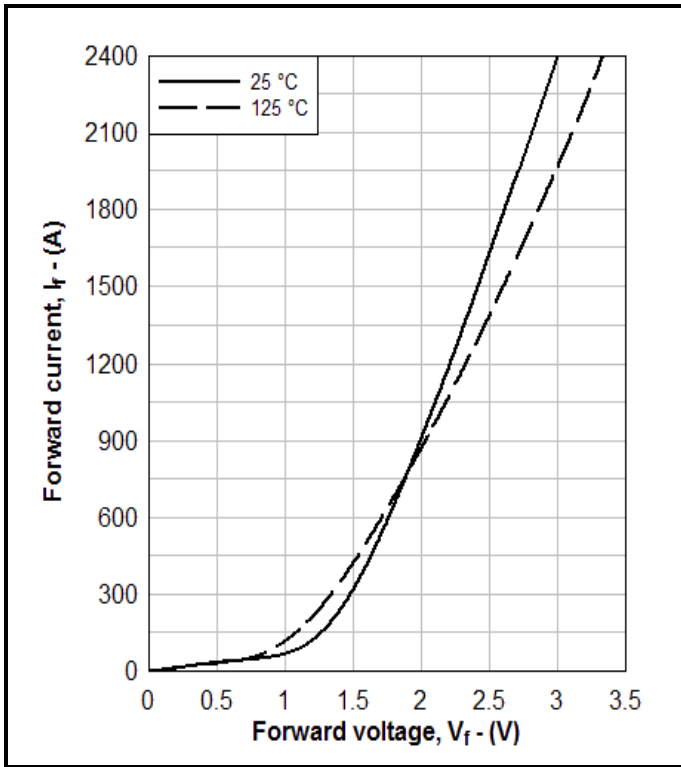


Fig. 3 Diode typical forward characteristics

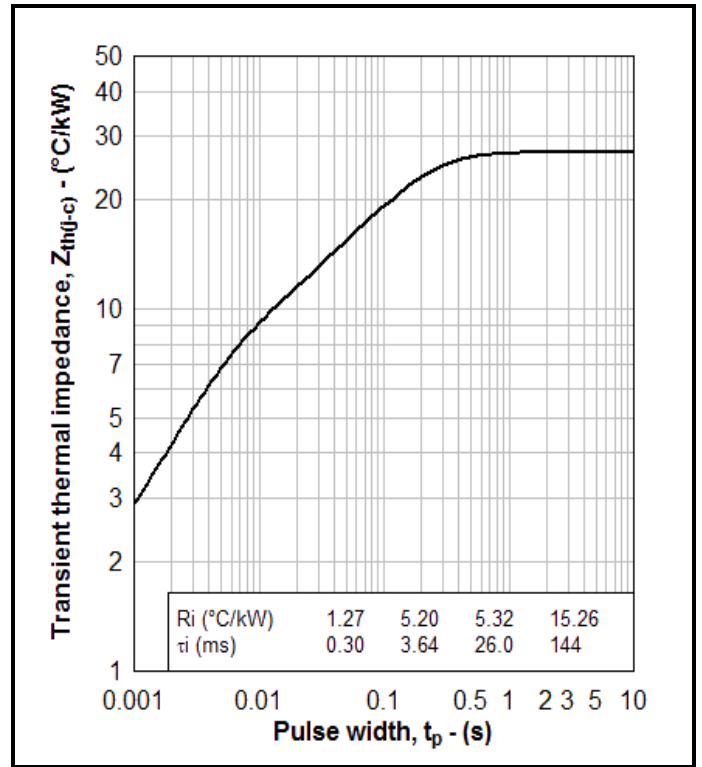


Fig. 4 Transient thermal impedance

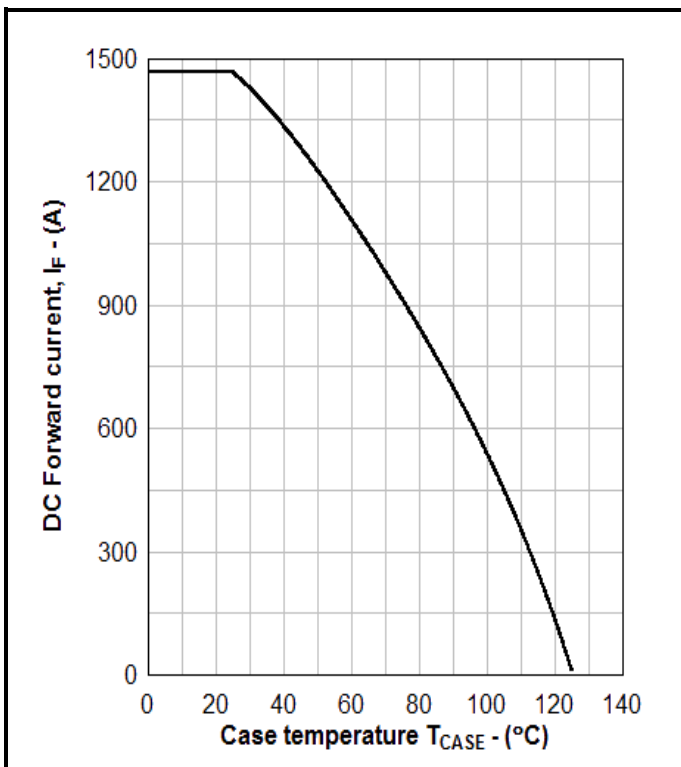


Fig. 5 DC Current rating vs case temperature

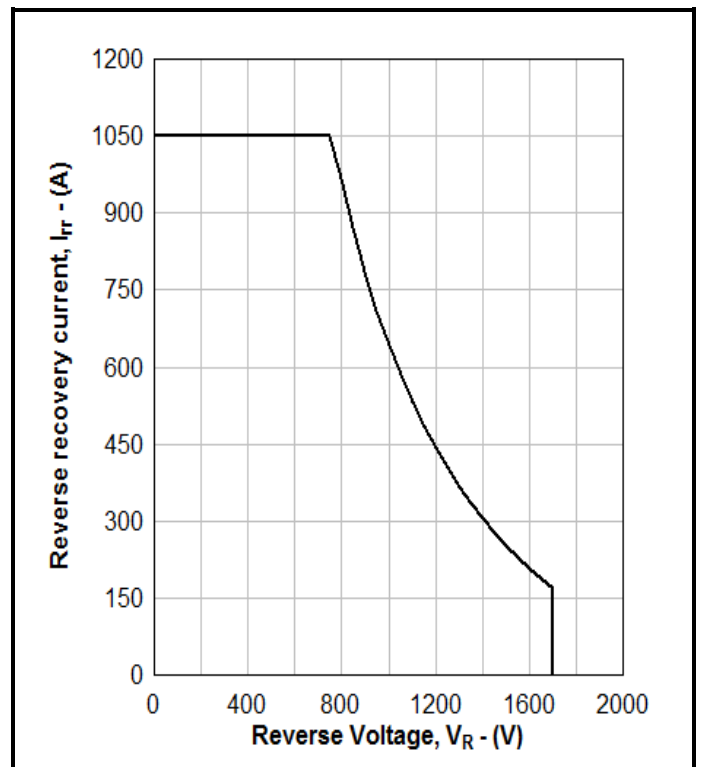
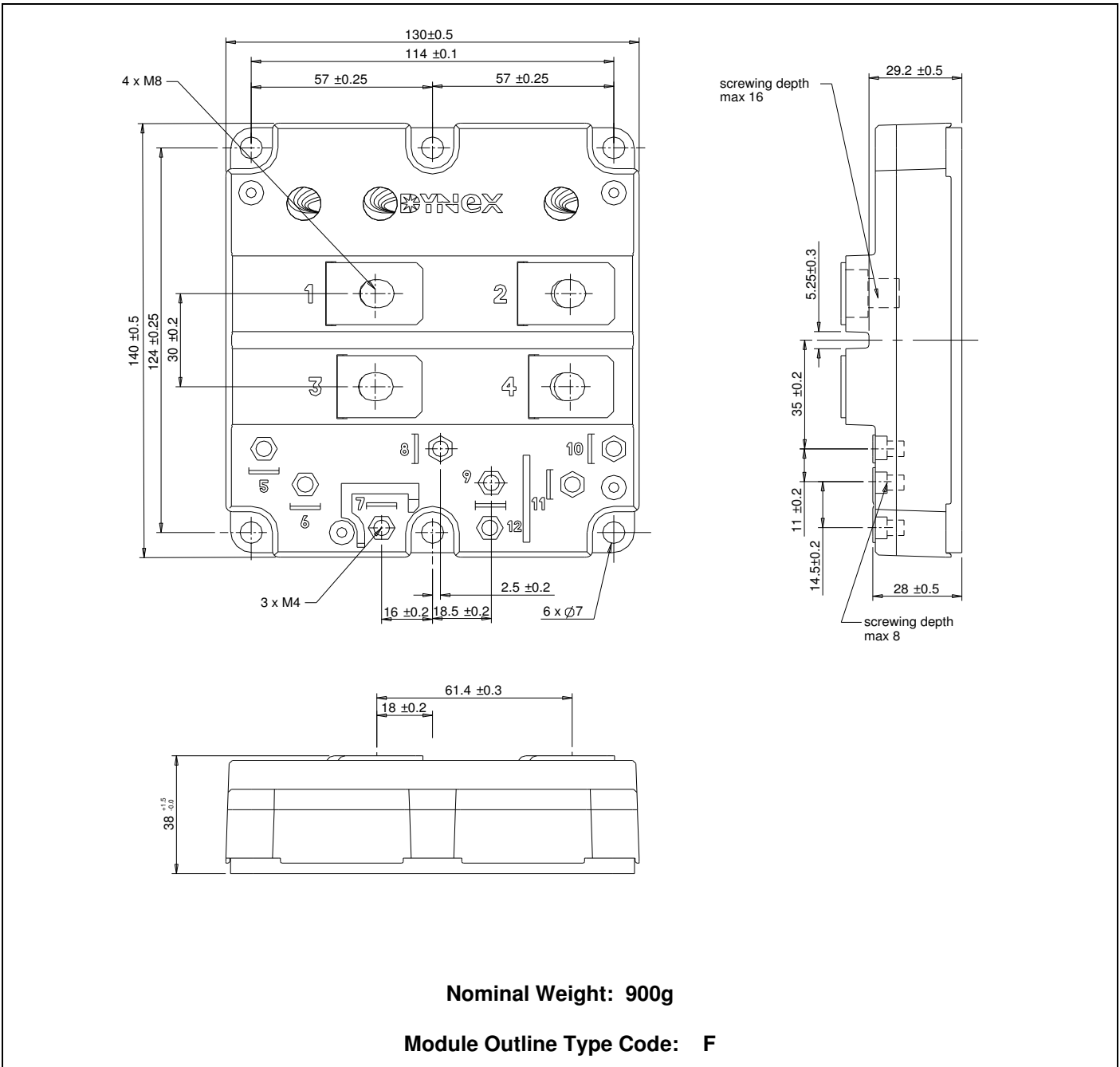


Fig. 6 RBSOA

PACKAGE DETAILS

For further package information, please visit our website or contact Customer Services.
 All dimensions in mm, unless stated otherwise.
DO NOT SCALE.



Nominal Weight: 900g

Module Outline Type Code: F

Fig. 7 Module outline drawing

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